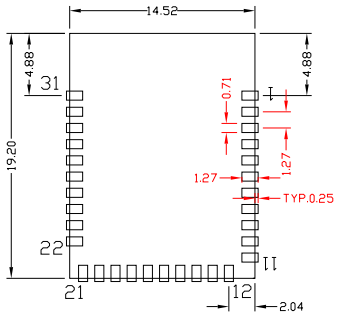
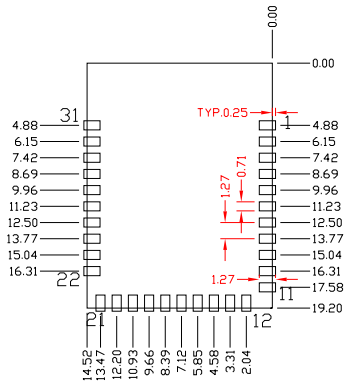
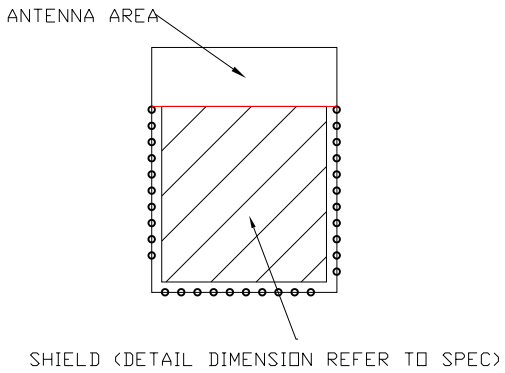
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1	INITIAL RELEASE	WW1701	

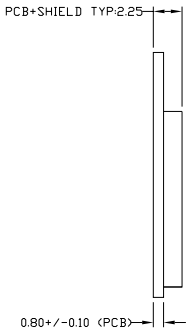
RECOMMEND PCB PATTERN



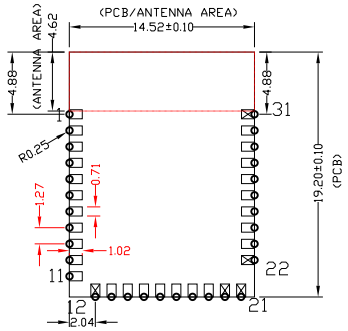




SEEN FROM TOP



SEEN FROM SIDE



SEEN FROM BOTTOM

MODULE PAD ASSIGNMENT:

PAD1:XRES
PAD2:GND/NC
PAD3:GND/NC
PAD4:P11/27
PAD5:P12/26
PAD6:P15
PAD7:P14/38
PAD8:P13/28
PAD9:P24
PAD10:NC
PAD11:NC
PAD12:P25
PAD13:P4
PAD14:P2
PAD15:VDD
PAD16:P3
PAD17:P8/33
PAD18:P32
PAD19:P1
PAD20:P0
PAD21:SDA
PAD22:SCL
PAD23:UP_TX
PAD24:UP_RX
PAD25:GND
PAD26:GND
PAD27:GND
PAD28:GND
PAD29:NC
PAD30:NC
PAD31:NC

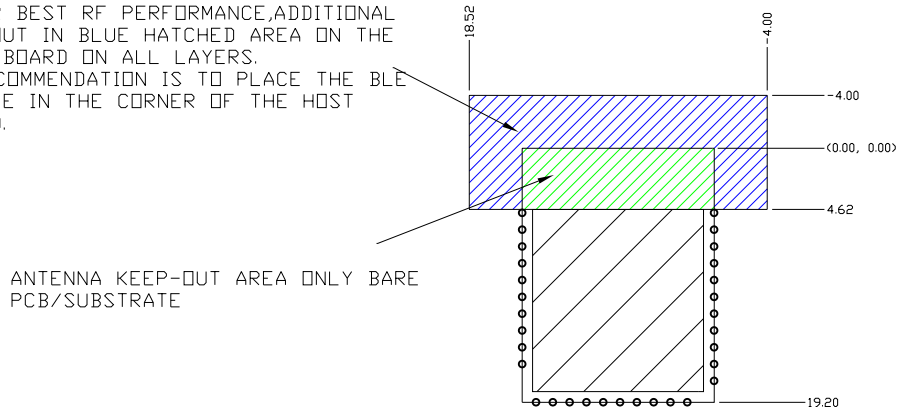


SCALE 1:1

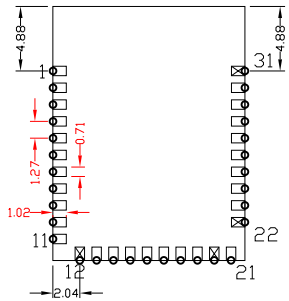
UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON; +/- 0.15 MM ANGLES +/-0.5 DEGREE	DRAWN: LINCOLN ZANG	WW1701	
	CHECKED		
	ENGRG		
	ISSUED		
			SIZE: REV NO: 0.1B; DWG NO
			SCALE 4:1; THE 3RD PROJECTION; SHEET: 1 OF 2

HOST PCB KEEP OUT AREA AROUND ANTENNA

1. FOR BEST RF PERFORMANCE,ADDITIONAL KEEPOUT IN BLUE HATCHED AREA ON THE HOST BOARD ON ALL LAYERS.
2. RECOMMENDATION IS TO PLACE THE BLE MODULE IN THE CORNER OF THE HOST BOARD.

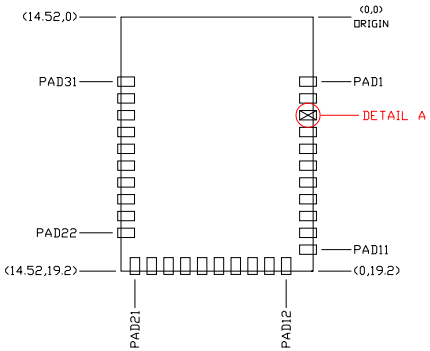


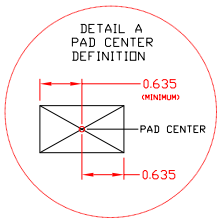
PAD DIMENSIONS



SOLDER PAD AND LOCATION

Solder Pad (Center of Pad)	Location (X,Y) from Origin (mm)	Dimension from Origin (mil)
1	(0.39, 4.88)	(15.35, 192.13)
2	(0.39, 6.15)	(15.35, 242.13)
3	(0.39, 7.42)	(15.35, 292.13)
4	(0.39, 8.69)	(15.35, 342.13)
5	(0.39, 9.96)	(15.35, 392.13)
6	(0.39, 11.23)	(15.35, 442.13)
7	(0.39, 12.50)	(15.35, 492.13)
8	(0.39, 13.77)	(15.35, 542.13)
9	(0.39, 15.04)	(15.35, 592.13)
10	(0.39, 16.31)	(15.35, 642.13)
11	(0.39, 17.58)	(15.35, 692.13)
12	(2.04, 18.82)	(80.31, 740.94)
13	(3.31, 18.82)	(130.31, 740.94)
14	(4.58, 18.82)	(180.31, 740.94)
15	(5.85, 18.82)	(230.31, 740.94)
16	(7.12, 18.82)	(280.31, 740.94)
17	(8.39, 18.82)	(330.31, 740.94)
18	(9.66, 18.82)	(380.31, 740.94)
19	(10.93, 18.82)	(430.31, 740.94)
20	(12.20, 18.82)	(480.31, 740.94)
21	(13.47, 18.82)	(530.31, 740.94)
22	(14.14, 16.31)	(556.69, 642.12)
23	(14.14, 15.04)	(556.69, 592.12)
24	(14.14, 13.77)	(556.69, 542.12)
25	(14.14, 12.50)	(556.69, 492.12)
26	(14.14, 11.23)	(556.69, 442.12)
27	(14.14, 9.96)	(556.69, 392.12)
28	(14.14, 8.69)	(556.69, 342.12)
29	(14.14, 7.42)	(556.69, 292.12)
30	(14.14, 6.15)	(556.69, 242.12)
31	(14.14, 4.88)	(556.69, 192.12)





UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.20 MM ANGLES +/-0.5 DEGREE	DRAWN: LINCOLN ZANG	WW1701	
	CHECKED		
	ENGRG		
	ISSUED		

SIZE	REV NO	DWG NO
	0.1B	

SCALE 4:1 | THE 3RD PROJECTION | SHEET: 2 OF 2